

ABSTRACT OF THE DISCLOSURE

**DOUBLE-DISK POLISHING MACHINE, PARTICULARLY FOR  
TOOLING SEMICONDUCTOR WAFERS**

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10 A double-disk polishing machine, particularly for tooling semiconductor wafers,  
comprising a machine housing, an upper and a lower working disk, carrier disks for the lower  
and upper working disks either of which is connected to a vertical driving shaft which, in turn,  
are rotatably supported in the machine housing by means of roller bearings and are adapted to be  
15 driven by a motor via a gear mechanism wherein cooling channels to which a coolant is fed are  
formed in each carrier disk, characterized in that each of the carrier disks is mounted with the aid  
of fastening means on a circumferential ring of a wheel-shaped basic carrier which, in turn, is  
connected to the driving shaft, the radius on which said fastening means lie which connect said  
basic carrier to said carrier disk is approximately on half the width of the ring-shaped working  
20 disk and said basic carrier for the upper working disk is connected to the shaft or to carrier disk  
in such a way that the inclination of the upper working disk automatically adapts itself to that of  
the lower working disk when the two working disks bear under a pressure against the interposed  
workpieces.